07-11-2000 FORM PTD-1595 U.S. DEPARTMENT OF COMMERCE 1-31-92 Patent and Trademark Office 101399906 To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. 1. Name of conveying party(les): 2. Name and address of receiving party(les): KATSUYOSHI WASHIO **MASAMICHI TANABE** REIKO HAYAMI Name: HITACHI, LTD. HIROMI SHIMAMOTO MASAO KONDO Katsuya oda Address: 6, Kanda Surugadai 4-Chome EIJI OUE CHIYODA-KU Additional name(s) of conveying party(ies) attached? 🗆 Yes 🔳 No City: TOKYO 3. Nature of conveyance: Assignment ... ☐ Merger Country: JAPAN ☐ Security Agreement 🗆 Change of Hame □ Other Execution Date: JUNE 7.9, 2000 Additional name(s) & address(es) attached? 🔳 Yes 🗆 No 4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date of the application is: JUNE 7,9, 2000 A. Patent Application No.(s) B. Patent No.(s) Additional numbers attached? 🗆 Yes 🔳 Ko 5. Name and address of party to whom correspondence concerning document should be 6. Total number of applications and patents involved: 1 mailed: .\$40.00 Mame: ANTONELLI, TERRY, STOUT & KRAUS, LLP 7. Total fee (37 CFR 3.41)_____ **Enclosed** Many deficiencies may be charged to deposit account Internal Address: □ Authorized to be charged to deposit account Street Address: 1300 North Seventeenth Street **Suite 1800** Zip: 22209 Deposit account number: 01-2135 State: VA City: Arlington Attached duplicate copy of this page if paying by deposit account) DO NOT USE THIS SPACE 9. Statement and Signature To the best of my knowledge and belief, the foregoing information is true and sorrect and any attached copy is a true copy of the original document \$ \$ L JUNE 23, 2000 **GREGORY E. MONTONE** Name of Person Signing Signature Attorney Registration No. 28,141 Total number of pages including cover sheet, attachments, and document: 3

OMB NO. 0651-0011 (Exp. 4/94)

PATENT

REEL: 010896 FRAME: 0177

ASSIGNMENT

(譲渡証)

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to the below named inventor(s), citizens of Japan by HITACHI, LTD., and Hitachi Device Engineering Co., Ltd., corporations organized under the laws of Japan,

located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, and 3681, Hayano, Mobara-Shi, Chiba, Japan, respectively,

receipt of which is hereby acknowledged, we, the below named inventor(s), do hereby sell and assign to said HITACHI, LTD., and Hitachi Device Engineering Co., Ltd.,

their successors and assigns, all our right, title and interest, in and for the United States of America, in and to SEMICONDUCTOR DEVICE

invented by us and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., and Hitachi Device Engineering Co., Ltd.,

their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by us if this assignment and sale had not been made;

And we hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of said above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And we do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD., and Hitachi Device Engineering co., Ltd.

Signed on the date(s) indicated aside our signatures:

RECORDED: 06/22/2000

INVENTOR(S)	Date Signed
(発明者フルネームサイン)	(署名日)
1) Catsuyoshi Washio	6/7/2000
2) Reiko Hayami	6/7/2000
3) Hirani Shinanoto	6/7/2000
4) Masaco Kondo	6/7/2000
5) Katsya Oda	6/7/2000
6) Eiji Ohne	6/7/2000
7) Masamichi Tanabe	6/9/2000
8)	
9)	
10)	

PATENT REEL: 010896 FRAME: 0178